5.0 V Dual TTL to Differential PECL Translator

The MC10ELT/100ELT22 is a dual TTL to differential PECL translator. Because PECL (Positive ECL) levels are used only +5 V and ground are required. The small outline 8-lead package and the low skew, dual gate design of the ELT22 makes it ideal for applications which require the translation of a clock and a data signal.

Features

- 1.2 ns Typical Propagation Delay
- < 300 ps Typical Output to Output Skew
- PNP TTL Inputs for Minimal Loading
- Flow Through Pinouts
- Operating Range: $V_{CC} = 4.75 \text{ V}$ to 5.25 V with GND = 0 V
- No Internal Input Pulldown Resistors
- Pb-Free Packages are Available



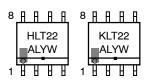
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http://onsemi.com

MARKING DIAGRAMS*



SO-8 D SUFFIX CASE 751









H = MC10

K = MC100

A = Assembly Location

L = Wafer Lot

Y = Year

W = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)
*For additional information, see Application Note
AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

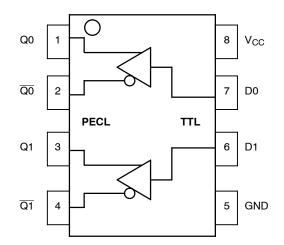


Table 1. PIN DESCRIPTION

Pin	Function
Qn, Qn	PECL Differential Outputs*
Dn	TTL Inputs
V _{CC}	Positive Supply
GND	Ground

^{*}Output state undetermined when inputs are open.

Figure 1. Logic Diagram and Pinout Assignment

Table 2. ATTRIBUTES

Characte	Value	
Internal Input Pulldown Resistor		N/A
Internal Input Pullup Resistor		N/A
ESD Protection	Human Body Model Machine Model	> 2 kV > 200 V
Moisture Sensitivity, Indefinite Ti	me Out of Drypack (Note 1)	Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count		51
Meets or exceeds JEDEC Spec	EIA/JESD78 IC Latchup Test	

^{1.} For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V _{CC}	Positive Power Supply	GND = 0 V		7	V
V _{IN}	Input Voltage	GND = 0 V		$\begin{array}{c} \text{GND} + 0.025 \leq V_{I} \\ \leq V_{CC} - 0.025 \end{array}$	V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	8 SOIC 8 SOIC	190 130	°C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	8 SOIC	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	8 TSSOP 8 TSSOP	185 140	°C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	8 TSSOP	41 to 44 ± 5%	°C/W
T _{sol}	Wave Solder	<2 to 3 sec @ 248°C		265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 4. 10ELT SERIES PECL DC CHARACTERISTICS V_{CC} = 5.0 V; GND = 0.0 V (Note 2)

		−40°C		25°C		85°C					
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{CC}	Power Supply Current			22			22			22	mA
V _{OH}	Output HIGH Voltage (Note 3)	3920	4010	4110	4020	4105	4190	4090	4185	4280	mV
V _{OL}	Output LOW Voltage (Note 3)	3050	3200	3350	3050	3210	3370	3050	3227	3405	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 2. Output parameters vary 1:1 with V_{CC} . V_{CC} can vary \pm 0.25 V.
- 3. Outputs are terminated through a 50 Ω resistor to V_{CC} 2.0 V.

Table 5. 100ELT SERIES PECL DC CHARACTERISTICS V_{CC} = 5.0 V; GND = 0.0 V (Note 4)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Icc	Power Supply Current			22			22			22	mA
V _{OH}	Output HIGH Voltage (Note 5)	3915	3995	4120	3975	4045	4120	3975	4050	4120	mV
V _{OL}	Output LOW Voltage (Note 5)	3170	3305	3445	3190	3295	3380	3190	3295	3380	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 4. Output parameters vary 1:1 with V_{CC} . V_{CC} can vary \pm 0.25 V.
- 5. Outputs are terminated through a 50 Ω resistor to V_{CC} 2.0 V.

Table 6. TTL INPUT DC CHARACTERISTICS $V_{CC} = 4.75 \text{ V}$ to 5.25 V; $T_A = -40 ^{\circ}\text{C}$ to $85 ^{\circ}\text{C}$

Symbol	Characteristic	Condition	Min	Тур	Max	Unit
I _{IH}	Input HIGH Current	$V_{IN} = 2.7 \text{ V};$ $V_{IN} = (V_{CC} - 0.025) \text{ V}$			20	μΑ
Іінн	Input HIGH Current	V _{IN} = 7.0 V			100	μΑ
I _{IL}	Input LOW Current	$V_{IN} = 0.5 \text{ V};$ $V_{IN} = (GND + 0.025) \text{ V}$			-0.6	mA
V _{IK}	Input Clamp Diode Voltage	I _{IN} = -18 mA			-1.2	V
V_{IH}	Input HIGH Voltage		2.0		V _{CC} - 0.025 V	V
V _{IL}	Input LOW Voltage		GND + 0.025 V		0.8	V

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

Table 7. AC CHARACTERISTICS V_{CC} = 4.75 V to 5.25 V; GND= 0.0 V

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{MAX}	Maximum Input Frequency					500					MHz
t _{PLH}	Propagation Delay (Note 6) 1.5 V to 50%	0.6		1.2	0.9	1.2	1.5	0.6		1.35	ns
t _{PHL}	Propagation Delay (Note 6) 1.5 V to 50%	0.4		1.0	0.5	0.8	1.1	0.7		1.30	ns
t _{skew}	Within-Device Skew (Note 7) Device-to-Device Skew (Note 8)		50 300	100 600		50 300	100 600		50 350	100 750	ps
t _{JITTER}	CLOCK Random Jitter (RMS)					0.5					ps
t _r /t _f	Output Rise/Fall Time (20-80%)	0.4		1.6	0.4		1.6	0.4		1.6	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 6. Specifications for standard TTL input signal.
- 7. Skew is measured between outputs under identical transitions and conditions on any one device.
- 8. Device-to-Device Skew for identical transitions at identical V_{CC} levels.

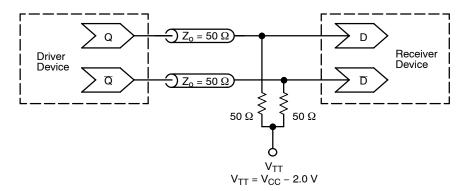


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping [†]
MC10ELT22D	SO-8	98 Units / Rail
MC10ELT22DG	SO-8 (Pb-Free)	98 Units / Rail
MC10ELT22DR2	SO-8	2500 Tape & Reel
MC10ELT22DR2G	SO-8 (Pb-Free)	2500 Tape & Reel
MC10ELT22DT	TSSOP-8	100 Units / Rail
MC10ELT22DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC10ELT22DTR2	TSSOP-8	2500 Tape & Reel
MC10ELT22DTR2G	TSSOP-8 (Pb-Free)	2500 Tape & Reel
MC100ELT22D	SO-8	98 Units / Rail
MC100ELT22DG	SO-8 (Pb-Free)	98 Units / Rail
MC100ELT22DR2	SO-8	2500 Tape & Reel
MC100ELT22DR2G	SO-8 (Pb-Free)	2500 Tape & Reel
MC100ELT22DT	TSSOP-8	100 Units / Rail
MC100ELT22DTG	G TSSOP-8 100 Units / (Pb-Free)	
MC100ELT22DTR2	TSSOP-8	2500 Tape & Reel
MC100ELT22DTR2G	TSSOP-8 (Pb-Free)	2500 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1672/D - The ECL Translator Guide
AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

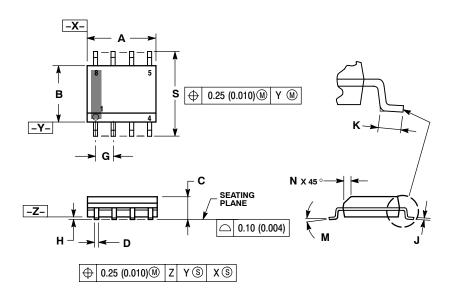
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

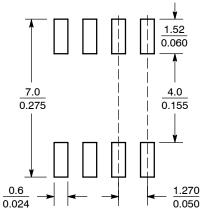
SOIC-8 NB CASE 751-07 **ISSUE AH**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A AND B DO NOT INCLUDE
 MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- MAXIMUM MIOLD PHOTHUSION 0.13 (0.000)
 PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT
- MAXIMUM MATERIAL CONDITION.
 751–01 THRU 751–06 ARE OBSOLETE. NEW STANDARD IS 751–07.

	MILLIN	IETERS	INC	HES		
DIM	MIN	MAX	MIN	MAX		
Α	4.80	5.00	0.189	0.197		
В	3.80	4.00	0.150	0.157		
С	1.35	1.75	0.053	0.069		
D	0.33	0.33 0.51		0.020		
G	1.27	7 BSC	0.050 BSC			
Н	0.10	0.25	0.004	0.010		
J	0.19	0.25	0.007	0.010		
K	(0.40 1.27		0.016	0.050		
M	0 ° 8 °		0 °	8 °		
N	0.25	0.50	0.010	0.020		
S	5.80	6.20	0.228	0 244		

SOLDERING FOOTPRINT*

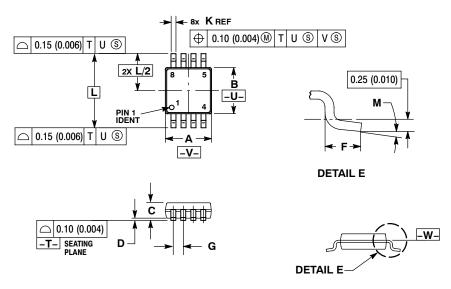


SCALE 6:1

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**



NOTES

- DIMENSIONS AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS.
- FLASH. PHOI HUSIONS OH GATE BURRS.
 MOLD FLASH OR GATE BURRS SHALL NOT
 EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE
 INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INCHES			
DIM	MIN	MIN MAX		MAX		
Α	2.90	3.10	0.114	0.122		
В	2.90	3.10	0.114	0.122		
С	0.80	1.10	0.031	0.043		
D	0.05	0.15	0.002	0.006		
F	0.40	0.70	0.016	0.028		
G	0.65	BSC	0.026	BSC		
K	0.25	0.40	0.010	0.016		
L	4.90	BSC	0.193 BSC			
M	0°	6 °	0°	6°		

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